

REMARKS

Claims 1-8 are pending. New claim 8 is added.

As a preliminary matter, an Information Disclosure Statement was filed on August 3, 2005. The Examiner is requested to acknowledge consideration of the IDS with the next communication.

Claims 1-3 were rejected under 35 USC §103(a) as being unpatentable over Obata et al. Presumably, the Examiner intended to also apply Hashimoto et al. as a secondary reference based on the Examiner's comments in the rejection. This rejection is respectfully traversed.

Obata et al. is cited for its disclosure of a probe. The Examiner acknowledges that Obata et al. does not disclose the claimed element supplementing unit which mounts additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe. Hashimoto et al. is applied for allegedly teaching this feature, and allegedly rendering it obvious to include this feature with the probe of Obata et al.

There is no motivation or suggestion to combine the references in a manner suggested by the Examiner.

Obata et al. is related to a structural improvement of a test device for testing a printed circuit board. On the other hand, Hashimoto et al. is directed to a package technique of a card type semiconductor device, having nothing to do with testing a printed circuit board. Hashimoto et al. does not provide any teaching or suggestion of a test device. Thus, there is no reason how

or why one of ordinary skill in the art would combine the teachings of the references in a manner which would render the claimed invention obvious.

Claims 1 to 3 of the present invention are drawn to a test apparatus which includes a probe and an element supplementing unit, and is characterized in that in each step of a process of fabricating a multilayer wiring board, the probe tests each newly added component and the wiring board is fixed or disposed of by the element supplementing unit when defects are detected. Only when defects are not detected, another component is added to proceed with fabrication of the multilayer wiring board.

Because Obata and Hashimoto are directed to completely different subject matter, there is no motivation of combining the teachings of these two references as stated by the Examiner, and even if the two references are combined, it cannot result in the advantages of the present invention.

The Examiner argues that it would have been obvious that after testing the printed wiring board, additional electronic compounds will be added. Thus, it appears that the Examiner does not understand that the claimed invention requires that the test apparatus itself include the claimed element supplementing unit. A combination of the prior art does not teach all of the claimed elements.

For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

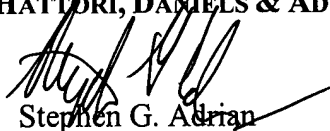
Amendment
Serial No. 10/664,930
Attorney Docket No. 021385B

Should the Examiner deem that any further action by applicant would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicant's undersigned attorney.

If this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP



Stephen G. Adrian

Attorney for Applicants
Registration No. 32,878
Telephone: (202) 822-1100
Facsimile: (202) 822-1111

SGA/arf